

TFT DISPLAY MODULE *Product Specification*

Customer	Standard	
Product Number	DMT028QVHXCMI-1A	
Customer Part Number		
Customer Approval		Date:

	Internal Approvals	
Product Mgr	Doc. Control	Electr. Eng
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Date: 01/07/17	Date: 01/07/17	Date: 01/07/17

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Rev.	Date	Page	Chapt.	Comment	ECR no.
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1.0 Main Features

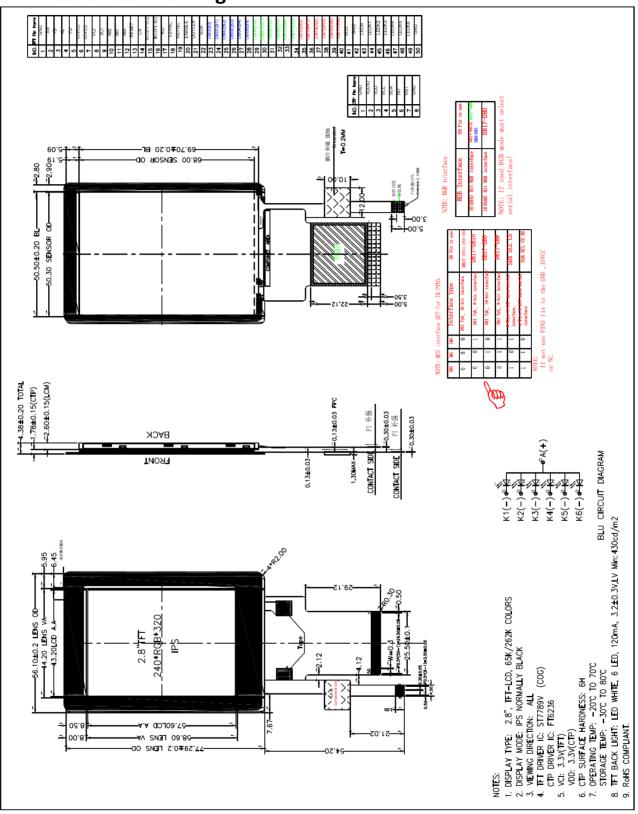
Item	Contents		
Screen Size	2.8" Diagonal		
Display Format	240 x RGB x 320 Dots		
N° of Colour	65K/262K		
Active Area	43.20 mm (V) x 57.60 mm (H)		
PCT View Area	44.20 (V) x 58.60 mm (H)		
LCD Type	TFT		
Mode	Transmissive / Normally Black		
Viewing Direction	ALL		
TFT Interface	8/9/16/18 bit 8080 MCU 3/4-wire SPI 3/4-wire SPI+16/18 bit RGB		
PCT Interface	12C		
TFT Driver IC	ST7789V		
PCT Driver IC	FT6236		
Simultaneous Touch Points	1		
Backlight Type	LED		
Operating Temperature	-20°C ~ +70°C		
Storage Temperature	-30°C ~ +80°C		
RoHS compliant	Yes		

2.0 Mechanical Specification

2.1 Mechanical Characteristics

Item	Characteristic	Unit
Overall Dimensions	56.10 mm (H) x 77.29 mm (V) x 4.38 mm (D)	mm
pixel Pitch	180 (H) x 180 (V)	μm
Weight	TBD	g

2.2 Mechanical Drawing



3.0 Electrical Specification

3.1 Absolute Maximum Ratings

3.1.1 TFT

Item	Symbol	Condition	Min	Max	Unit	Note
Power Supply Voltage LCM	VCI		-0.3	4.6	V	
Digital Interface Supply Voltage	IOVCC		-0.3	4.6	V	
Operating Temperature	ТОР		-20	70	°C	1
Storage Temperature	TST		-30	80	°C	1,2,3

Note 1. 90 % RH Max for Ta<50 °C, and 60% RH for Ta≥50°C.

- **Note 2.** In case of below 0°C, the response time of liquid crystal (LC) becomes slower and the colour of panel becomes darker than normal one. Level of retardation depends on temperature, because of LC's characteristic.
- **Note 3.** Only operation is guaranteed at operating temperature. Contrast, response time, another display quality are evaluated at +25°C.

3.1.2 PCT

Item	Symbol	Condition	Min	Max	Unit	Note
Power Supply Voltage	VDD		-0.3	3.6	V	4
Operating Temperature	ТОР		-20	70	°C	-
Storage Temperature	TST		-30	80	°C	-

Note 4. If used beyond the absolute maximum ratings, FT6236 may be permanently damaged. It is strongly recommended that the device be used within the electrical characteristics in normal operations. If exposed to the condition not within the electrical characteristics, it may affect the reliability of the device.

3.2 Electrical Characteristics

3.2.1 TFT

Item	Symbol	Condition	Min	Тур	Max	Unit	Note
Supply Voltage	VCI	Ta=25°C	2.4	2.8	3.3	V	
Digital Interface Supply Voltage	IOVCC	Ta=25°C	1.65	1.8	3.3		
	VIH		0.7IOVCC	-	IOVCC	V	
Input Voltage for Logic	GND		GND	-	0.3 IOVCC	V	
Output Voltage for	VOH		0.8IOVCC	-	IOVCC	V	
Logic	VOL		GND	-	0.2IOVCC	V	
Current Consumption	IDD		-	6.8	-	mA	1

Note 1: The specified power consumption is under the conditions of VDD=3.3V.

3.2.2 PCT

ltem	Symb ol	Condition	Min	Тур	Max	Unit	Note
Supply Voltage	VDD		2.8	3.3	3.6	V	
Input Voltage for	VIH		0.7 VDDIO	-	VDDIO	V	
Logic	VIL		-0.3	-	0.3 VDDIO	V	
Output Voltage for	VOH	IOH = 01.mA	0.7 VDDIO	-	-	V	
Logic	VOL		-	-	0.3 VDDIO	V	
Normal operation mode Current Consumption	IOPR	VDD=2.8V	-	4	-	mA	
Monitor mode Current Consumption	IMON	Ta=25°C MCLK= 17.5MHz	-	1.5	-	mA	
Sleep mode Current Consumption	ISLP		-	50	-	uA	

3.3 Interface Pin Assignment

3.3.1 TFT Pin Assignment

No.	Symbol	Function
1	GND	Ground.
2	XR(NC)	Touch panel Right Glass Terminal
3	YD(NC)	Touch panel Bottom Film Terminal
4	XL(NC)	Touch panel LIFT Glass Terminal
5	YU(NC)	Touch panel Top Film Terminal
6	IOVCC	Supply voltage for IO (1.8-3.3V). Supply voltage for IO (1.8-3.3V). Supply voltage (3.3V).
7	IOVCC	Red data input.
8	VCI	Red data input.
9	VCI	Supply voltage (3.3V).
10	IM2	MPU Parallel interface bus and serial interface select If use RGB Interface must select serial interface. Fix this pin at IOVCC and GND.
11	IM1	Line synchronizing signal for RGB Interface mode. If not used, please connect to GND or IOVCC.
12	IM0	Pixel clock signal for RGB Interface mode. If not used, please connect to GND or IOVCC.
13	RESET	This signal will reset the device and must be applied to properly initialize the chip.
14	CS	Chip select input pin ("Low" enable). Fix this pin at IOVCC or GND when not in use.
15	RS(SPI- SCL)	This pin is used to select "Data or Command" in the parallel interface. When D/CX = '1', data is selected. When D/CX = '0', command is selected. This pin is used serial interface clock in 3-wire 9-bit / 4-wire 8-bit serial data interface. Fix this pin at IOVCC or GND when not in use.
16	WR(SPI- RS)	The data is applied on the rising edge of the SCL signal. Fix this pin at IOVCC or GND when not in use.
17	RD	Serves as a read signal and MCU read data at the rising edge. Fix this pin at IOVCC or GND when not in use
18	VSYNC	Frame synchronizing signal for RGB interface operation. Fix this pin at IOVCC or GND when not in use.
19	HSYNC	Line synchronizing signal for RGB interface operation. Fix this pin at IOVCC or GND when not in use.

No.	Symbol	Function
20	ENABLE	Data enable signal for RGB interface operation. Fix this pin at IOVCC or GND when not in use.
21	DOTCLK	Dot clock signal for RGB interface operation. Fix this pin at IOVCC or GND when not in use.
22	SDA	Serial input signal. The data is applied on the rising edge of the SCL signal. If not used, fix this pin at IOVCC or GND.
23-40	DB0- DB7	Data bus. If not used pin, fix this pin to GND.
41	SDO	SPI interface output pin. -The data is output on the falling edge of the SCL signal. -If not used, let this pin open.
42	GND	Ground.
43	LEDA	Anode pin of backlight
44	LEDK1	Cathode pin OF backlight
45	LEDK2	Cathode pin OF backlight
46	LEDK3	Cathode pin OF backlight
47	LEDK4	Cathode pin OF backlight
48	LEDK5	Cathode pin OF backlight
49	LEDK6	Cathode pin OF backlight
50	GND	Ground.

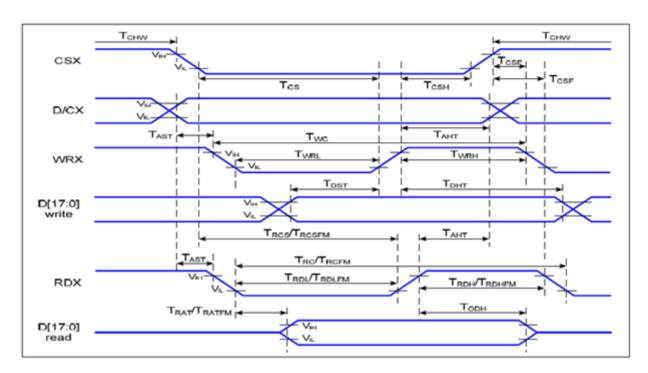
3.3.2 PCT PIN ASSIGNMENT

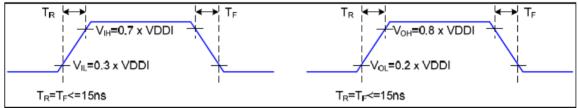
NO.	SYMBOL	DISCRIPTION
1	GND	Ground.
2	VDDIO	I/O power supply voltage
3	VDD	Supply voltage.
4	SCL	I2C clock input.
5	SDA	I2C data input and output
6	INT	External interrupt to the host.
7	RST	External Reset, Low is active.
8	GND	Ground.

3.4 Timing Characteristics

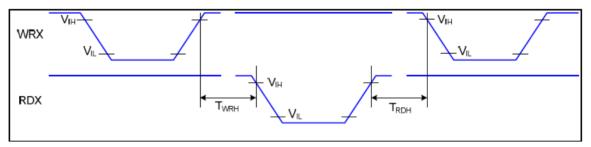
3.4.1 AC Characteristics

8080 Series MCU parallel interface timing characteristics: 18/16/9/8-bit bus





Rising and Falling Timing for I/O Signal



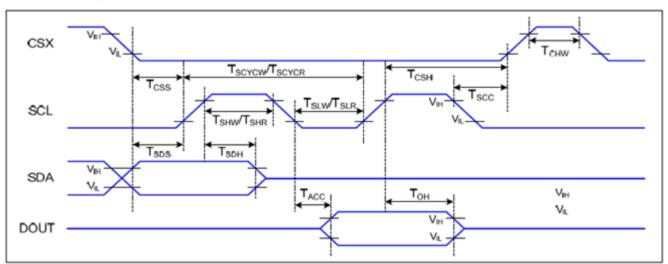
Write-to-Read and Read-to-Write Timing

Note: The rising time and falling time (Tr, Tf) of input signal and fall time are specified at 15 ns or less. Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.

Signal	Symbol	Parameter	Min	Мах	Unit	Description
D/CX	T _{AST}	Address setup time	0		ns	
DICA	T _{AHT}	Address hold time (Write/Read)	10		ns	-
	T _{CHW}	Chip select "H" pulse width	0		ns	
csx	T _{cs}	Chip select setup time (Write)	15		ns	
	T _{RCS}	Chip select setup time (Read ID)	45		ns	
COA	T _{RCSFM}	Chip select setup time (Read FM)	355		ns	-
	T _{CSF}	Chip select wait time (Write/Read)	10		ns	
	T _{CSH}	Chip select hold time	10		ns	
	T _{wc}	Write cycle	66		ns	
WRX	T _{WRH}	Control pulse "H" duration	15		ns	
	T _{WRL}	Control pulse "L" duration	15		ns	
	T _{RC}	Read cycle (ID)	160		ns	
RDX (ID)	T _{RDH}	Control pulse "H" duration (ID)	90		ns	When read ID data
	T _{RDL}	Control pulse "L" duration (ID)	45		ns	
RDX	TRCFM	Read cycle (FM)	450		ns	When read from
(FM)	TRDHFM	Control pulse "H" duration (FM)	90		ns	frame memory
(('W))	T _{RDLFM}	Control pulse "L" duration (FM)	355		ns	Inditie memory
D[17:0]	T _{DST}	Data setup time	10		ns	For CL=30pF
	T _{DHT}	Data hold time	10		ns	
	T _{RAT}	Read access time (ID)		40	ns	
	TRATEM	Read access time (FM)		340	ns	
	TODH	Output disable time	20	80	ns	

3.4.2 Display Serial Interface Timing Characteristics

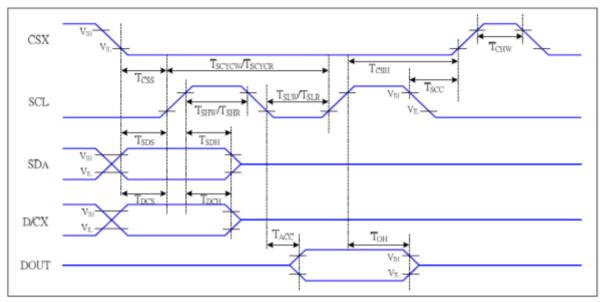
IOVCC = 1.65 to 3.3V VCI = 2.4 to 3.3V AGND = DGND = 0V Ta = -30 to $70^{\circ}C$



3-line SPI system

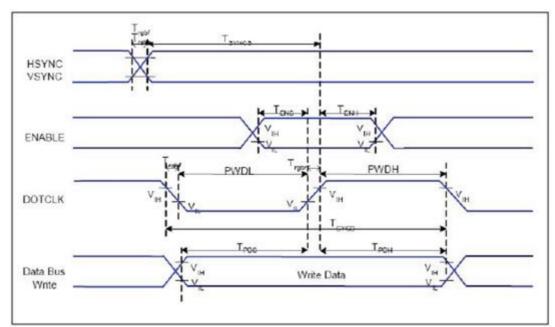
Signal	Symbol	Parameter	Min	Мах	Unit	Description
	T _{CSS}	Chip select setup time (write)	15		ns	
	T _{CSH}	Chip select hold time (write)	15		ns	
CSX	T _{CSS}	Chip select setup time (read)	60		ns	
	T _{SCC}	Chip select hold time (read)	65		ns	
	T _{CHW}	Chip select "H" pulse width	40		ns	
	T _{SCYCW}	Serial clock cycle (Write)	66		ns	
	T _{SHW}	SCL "H" pulse width (Write)	15		ns	
SCL	T _{SLW}	SCL "L" pulse width (Write)	15		ns	
SCL	T _{SCYCR}	Serial clock cycle (Read)	150		ns	
	T _{SHR}	SCL "H" pulse width (Read)	60		ns	
	T _{SLR}	SCL "L" pulse width (Read)	60		ns	
SDA	T _{SDS}	Data setup time	10		ns	
(DIN)	T _{SDH}	Data hold time	10		ns	
DOUT	T _{ACC}	Access time	10	50	ns	For maximum CL=30pF
0001	Тон	Output disable time	15	50	ns	For minimum CL=8pF





Signal	Symbol	Parameter	MIN	MAX	Unit	Description
Signal CSX SCL D/CX SDA (DIN) DOUT	T _{CSS}	Chip select setup time (write)	15		ns	
	T _{CSH}	Chip select hold time (write)	15		ns	
	T _{CS5}	Chip select setup time (read)	60		ns	
	Tscc	Chip select hold time (read)	65		ns	
	TCHW	Chip select "H* pulse width	40		ns	
SCL	Tscycw	Serial clock cycle (Write)	66		ns	write commond 8 date
	T _{SHW}	SCL "H" pulse width (Write)	15		ns	-write command & data
	Tslw	SCL "L" pulse width (Write)	15		ns	ram
	TSCYCR	Serial clock cycle (Read)	150		ns	and some and 6 data
	TSHR	SCL "H" pulse width (Read)	60		ns	-read command & data
	T _{SLR}	SCL "L" pulse width (Read)	60		ns	ram
DVOY	Toos	D/CX setup time	10		ns	
D.A. X	TDCH	D/CX hold time	10		ns	
SDA	T _{SDS}	Data setup time	10		ns	
(DIN)	T _{SOH}	Data hold time	.10		ns	
	TACC	Access time	10	50	ns	For maximum CL=30pF
0001	Тон	Output disable time	15	50	ns	For minimum CL=8pF

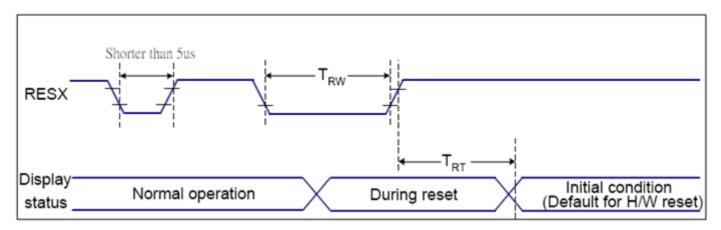
3.4.3 Parallel RGB Interface Timing Characteristics



IOVCC = 1.65 to 3.3V VCI = 2.4 to 3.3V AGND = DGND = 0V Ta = -30 to 70°C

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
HSYNC, VSYNC	T _{SYNCS}	VSYNC, HSYNC Setup Time	30	-	ns	
ENABLE	T _{ENS}	Enable Setup Time	25	-	ns	
LINADLE	T _{ENH}	Enable Hold Time	25	-	ns	
	PWDH	DOTCLK High-level Pulse Width	60	-	ns	
DOTCLK	PWDL	DOTCLK Low-level Pulse Width	60	-	ns	
DOTCLK	T _{CYCD}	DOTCLK Cycle Time	120	-	ns	
	Trghr, Trghf	DOTCLK Rise/Fall time	-	20	ns	
DB	T _{PDS}	PD Data Setup Time	50	-	ns	
00	T _{PDH}	PD Data Hold Time	50	-	ns	

3.4.4 Reset Timing Characteristics



IOVCC = 1.65 to 3.3V VCI = 2.4 to 3.3V AGND = DGND = 0V Ta = -30 to 70°C

Related Pins	Symbol	Parameter	MIN	MAX	Unit
	TRW	Reset pulse duration	10	-	us
RESX	TDT	Poset cancel	-	5 (Note 1, 5)	ms
	TRT Reset cancel			120 (Note 1, 6, 7)	ms

Note:

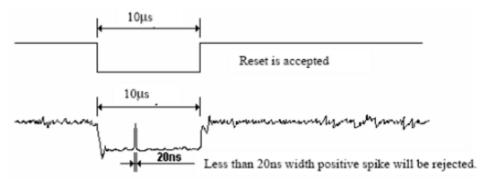
1. The reset cancel includes required time for loading the ID bytes, VCOM setting and other settings from NVM (or similar device) to registers. This loading is done every time when there is a HW reset cancel time (tRT) within 5 ms after a rising edge of RESX.

2. Spike due to an electrostatic discharge on RESX line does not cause irregular system resets according to the table below:

RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 9us	Reset
Between 5us and 9us	Reset starts

3. During the reset period, the display will be blank (Maximum time 120 ms, when reset starts in sleep out mode. The display remains in a blank state in sleep in mode). It will then return to the default condition for a hardware reset.

4. Spike rejection also applies during a valid reset pulse as shown below:



5. Reset is applied during sleep in mode.

6. Reset applied during sleep out mode

7. It is necessary to wait 5msec after releasing RESX before sending commands. The sleep out command cannot be sent for 120msec.

3.5.1 I2C Interface

The I2C is always configured in the Slave mode. The data transfer format is shown in Figure4-1:

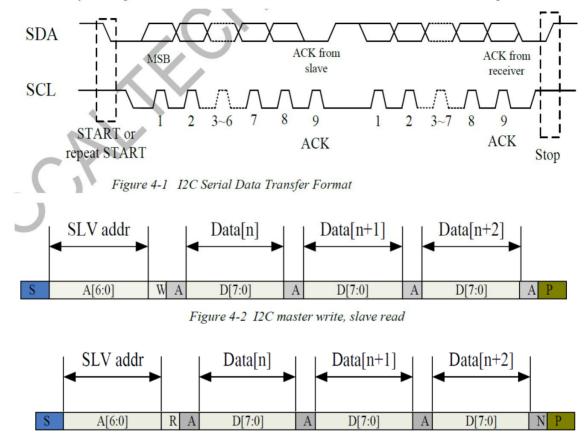


Figure 4-3 I2C master read, slave write

Table4-3 lists the meanings of the mnemonics used in the above figures.

Table 4-3 Mnemonics Description

Mnemonics	Description
S	I2C Start or I2C Restart
A[6:0]	Slave address
R/W	READ/WRITE bit, '1' for read, '0' for write
A(N)	ACK(NACK)
Р	STOP: the indication of the end of a packet (if this bit is missing, S will indicate the end of the current packet and the beginning of the next packet)

I2C Interface Timing Characteristcs is shown in Table4-4.

Table 4-4 I2C Timing Characteristics

Parameter	Min	Max	Unit
SCL frequency	10	400	KHz
Bus free time between a STOP and START condition	4.7	١	us
Hold time (repeated) START condition	4.0	١	us
Data setup time	250	١	ns
Setup time for a repeated START condition	4.7	١	us
Setup Time for STOP condition	4.0	١	us

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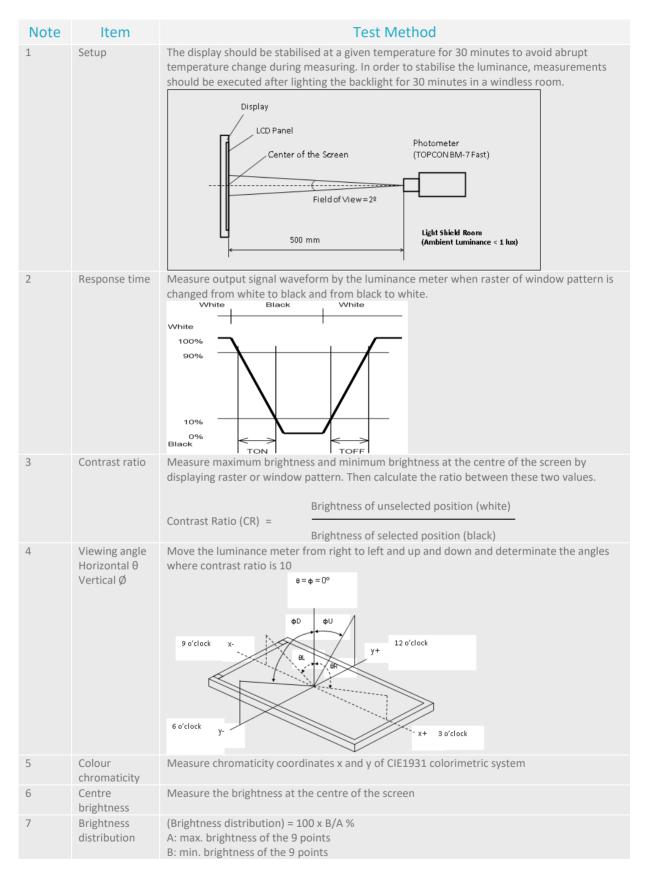
4.0 Optical Specification

4.1 Optical Characteristics

Measuring instruments :	LCD-5100, Eldim, Topcon BM-7
Driving condition:	VDD = 3.3V, VSS = 0V
Backlight:	IF=40mA
Measured temperature:	Ta = 25 °C

lt	em	Symbol	Condition	Min	Тур	Max	Unit	Note
Respo	Response Time		θ=Φ=0°	-	30	40	ms	2
Contra	ast Ratio	CR	Normal Viewing Angle	600	800	-		3
e	Left	θL		-	80	-	deg	4
Viewing Angle	Right	θR		-	80	-	deg	
ewing	Up	φU	CR ≥ 10	-	80	-	deg	
<i<< td=""><td>Down</td><td>φD</td><td></td><td>-</td><td>80</td><td>-</td><td>deg</td><td></td></i<<>	Down	φD		-	80	-	deg	
	Red	Rx	CR ≥ 10	0.613	0.633	0.653	-	
		Ry		0.325	0.345	0.365	-	5
Colour Chromaticity		Gx		0.311	0.331	0.351	-	
Iroma	Green	Gy		0.600	0.620	0.640	-	
ur Ch	Blue	Bx		0.125	0.145	0.165	-	
Colo	Blue	Ву		0.048	0.068	0.088	-	
	White	Wx		0.268	0.308	0.348	-	
	vvince	Wy		0.288	0.328	0.368	-	
Centre Brightness			580	630	-	cd/m²	6	
Brigh	ntness Dist	ribution		80	-	-	%	7

4.1.1 Test Method



5.0 Backlight Specification

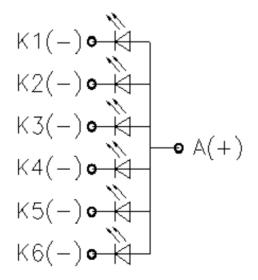
5.1 LED Driving Conditions

Item	Symbol	Condition	Min	Тур	Max	Unit
Forward Current	IF	Ta=25 °C	90	120	-	mA
Forward Voltage	VF	Ta= 25°C		3.2		V
LED life time	Hr				50k	hour

Note:

- The lifetime of the LED is defined as a period till the brightness of the LED decreases to the half of its initial value.
- This figure is given as a reference purpose only, and not a guarantee.
- This figure is estimated for an LED operating alone. The performance of an LED may differ when assembled as a monitor together with a TFT panel due to different environmental temperature.
- Estimated lifetime could vary on a different temperature and usually higher temperature could reduce the life significantly.

5.2 LED Circuit



BLU CIRCUIT DIAGRAM

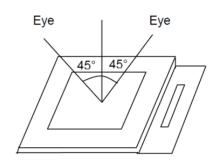
LED Circuit Drawing

6.0 Quality Assurance Specification

6.1 Delivery Inspection Standards

6.1.1 Inspection Conditions

Inspection distance: $30 \text{ cm} \pm 2 \text{ cm}$ Viewing angle: $\pm 45^{\circ}$



6.1.2 Environmental Conditions

Ambient temperature:	25°C ±5°C
Ambient humidity:	65±10% RH
Ambient illumination:	300~700 lux

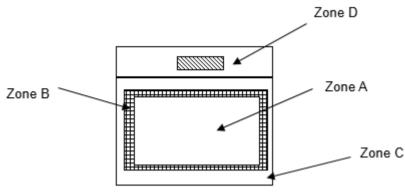
6.1.3 Sampling Conditions

- 1. Lot size: quantity of shipment lot per model
- 2. Sampling method:

Sampling Plan		GB/T 2828-2003		
		Normal inspection, Class II		
AQL	Major Defect	0.65%		
	Minor Defect	1.5%		

No	Items to be inspected	Criteria	Classification of defects
1	Functional defects	 No display, Open or miss line Display abnormally, Short Backlight no lighting, abnormal lighting. TP no function 	Major
2	Missing	Missing component	
3	Outline dimension	Overall outline dimension beyond the drawing is not allowed	
4	Color tone	Color unevenness, refer to limited sample	
5	Spot Line defect	Light dot , Dim spot,Polarizer Bubble ; Polarizer accidented spot.	Minor
6	Soldering appearance	Good soldering , Peeling off is not allowed.	

6.1.4 Definition of Area



Zone A : Effective Viewing Area(Character or Digit can be seen)

Zone B : Viewing Area except Zone A

Zone C : Outside (Zone A+Zone B) which can not be seen after assembly by customer .)

Zone D : IC Bonding Area

Note:

As a general rule ,visual defects in Zone C can be ignored when it doesn't effect product function or appearance after assembly by customer

6.1.5 Basic Principle

A set of sample to indicate the limit of acceptable quality level shall be discussed should a dispute occur.

6.1.6 Inspection Criteria

Number	Items	Criteria(mm)
1.0 LCD Crack/Broken NOTE: X: Length Y: Width Z: Height L: Length of ITO, T: Height of LCD	(1) The edge of LCD broken	X Y Z ≤ 3.0 mm <inner border="" line="" of="" seal<="" td="" the=""> $\leq T$</inner>
	(2)LCD corner broken	$\begin{array}{c c} \hline \\ \hline $
	(3) LCD crack	Crack Not allowed

		1 light dot (LCD/TP/Pola	arizer black/white sp	ot , light dot,	pinhole, dent, stain)		
		Zone	A	Acceptable Q	table Qty		
		Size (mm)	A	В	С		
		Ф≤0.10	Ignor	re			
		0.10<Φ≤0.25	3(distance≧10mm)				
		0.25<Φ≤0.3 2		lgnore			
		Φ>0.35	0				
		②Dim spot (LCD/TP/Pola	arizer dim dot, light l	eakage、 dar	k spot)		
		Zone	A	Acceptable Q	ty		
		Size (mm)	А	В	С		
		Ф≤0.1	Ignor	e			
		0.10<Ф≤0.25	3(distance≧	≧10mm)	lgnore		
		0.25<Ф≤0.3	2		ignore		
		Φ>0.35	0				
Spot defect	(3) Polarizer accidented sp						
		Zone Size (mm)	Acceptable Qty		ty		
			A	В	С		
	x	Φ≤0.2	lgnor				
		0.3<Φ≤0.5	2(distance≧	lgnore			
Φ	Φ=(X [‡] Y)/2	Φ>0.5	0				
		④Pixel bad points (light d	lot, Dim dot, color d	color dot)			
		Zone		Qty			
		Size (mm)	А		в С		
2.0		Ф≤0.1	lgnore		I		
		0.15<Φ≤0.25	2(distance≧10m	ım)	Ignore		
		Ф>0.3	0				
		5 Polarizer Bubble					
	Zone		Acceptable Qty		ty		
		Size (mm)	А	В	С		
		Ф≤0.2	Ignore				
		0.3<Ф≤0.4	3(distance	≧10m)			
		0.5<Φ≤0.6	2		lgnore		
		0.6<Φ	0		—		

				Vidth(mm)	Length(mm)		Acceptable Qty										
(LCE	Line de	fect		width(mm) Lei		А	В	С									
	(LCD/ ⁻ /Polari			Ф≤0.05	lgnore	lgr	nore										
2.0	backlig	ght	0.0	05 <w≤0.06< td=""><td>L≤4.0</td><td>N</td><td> ≤3</td><td>lgnore</td></w≤0.06<>	L≤4.0	N	≤3	lgnore									
3.0	black/whit scratch, s		0.0	07 <w≤0.08< td=""><td>L≤3.0</td><td>N</td><td> ≤2</td><td></td></w≤0.08<>	L≤3.0	N	≤2										
				0.08 <w< td=""><td></td><td colspan="3">Define as spot defect</td></w<>		Define as spot defect											
4.0	Electronic Componer SMT	its	Not allow missing parts, sole The positive and negative pol			nection,cold solder joint,mismatch, ite											
5.0	Display col Brightness		g to 2. Brig	g to the datasheet or samples.													
						Accep	otable Qty										
			Cover	Size Φ(mm)	А		В	C									
												nsor ented	Ф≤0.1		Ignore		
		black/v spo		0.1<Φ≤0.2	3(dis	$3(distance \ge 10 mm)$											
			oot	0.20<Φ≤0.25		2		lgnore									
			Φ > 0.3			0											
6.0					. ,	,	Accepta	ble Qty									
	РСТ			Width(mm)	Ignore(m	m) A	E	3 C									
	Related	PCT	Cover	Ф≤0.05	Ignore		Igno	ore									
		scra	atch	0.05 <w≤0.06< td=""><td>L≤4.0</td><td></td><td>N≤</td><td>≤3</td></w≤0.06<>	L≤4.0		N≤	≤3									
				0.07 <w≤0.08< td=""><td>L≤3.0</td><td></td><td>N≤</td><td>≤2</td></w≤0.08<>	L≤3.0		N≤	≤2									
				0.08 <w< td=""><td></td><td>Define a</td><td>s spot defe</td><td>ct</td></w<>		Define a	s spot defe	ct									
						Accep	table Qty										
				Zone Size (mm)			С										
		PCT Co		Φ≤0.1		ا	gnore										
	1	Pinhole Lack of		0.1<Φ≤0.2		3(distan	ce≧10mm)									
				0.25<Φ≤0.3			2										
				Φ>0.35			0										
		PCT Bonding		Size Φ(mm)		Accep A	btable Qty B										
			onding ble/	Ф≤0.1		Ignore	1										
			ented	0.15<Φ≤0.2			e≧10mm)									
	spc		oot	0.2<Φ≤0.25		2											
				Φ>0.25		0											

	Assembly deflection	beyond the ed	dge of backli	ight ≤0.2mm	
	TP cover broken X : length Y : width Z : height	X X≤0.5mm * Circuitry bro	Y Y≤0.5m m	Z Z <cover thickness</cover 	x
	TP cover broken X : length Y : width Z : height	X X≤0.3mm * Circuitry bro	Y Y≤0.3mm oken is not a	Z Z <lcd thickness</lcd 	z

Criteria (functional items)

Number	Items	Criteria (mm)
1	No display	Not allowed
2	Missing segment	Not allowed
3	Short	Not allowed
4	Backlight no lighting	Not allowed
5	TP no function	Not allowed

6.1.7 Classification of Defects

Visual defects (except no or wrong label) are treated as minor defects, while electrical defects are treated as major defects.

Two minor defects are equal to one major defect in lot sampling inspection.

6.1.8 Identification / marking criteria

Any unit with illegible / wrong / double or no marking / label shall be rejected.

6.2 Dealing with Customer Complaints

6.2.1 Non-conforming analysis

Purchaser should supply Densitron with detailed data of non-conforming sample. After accepting it, Densitron should complete the analysis in two weeks from receiving the sample.

If the analysis cannot be completed on time, Densitron must inform the purchaser.

6.2.2 Handling of non-conforming displays

If any non-conforming displays are found during customer acceptance inspection which Densitron is clearly responsible for, return them to Densitron.

Both Densitron and customer should analyse the reason and discuss the handling of nonconforming displays when the reason is not clear.

Equally, both sides should discuss and come to agreement for issues pertaining to modification of Densitron quality assurance standard.

7.0 Reliability Specification

7.1 Reliability Tests

Test Item		Test (Sample Size	
	High Temperature Operation	1a = 700 96n		3pcs
	Low Temperature Operation	Ta=-20°C	96h	3pcs
	High Temperature Storage	Tp= 80°C	96h	3pcs
	Low Temperature Storage Tp= -30°C		96h	3pcs
y Test	ESD Test	150pF, 330Ω, ±6l (Air), 5 Points/pa	3pcs	
Durability Test	Thermal Shock Resistance	The sample shou stand the followi operation: LTS for normal temperat HTS for 30 minut temperature for cycle, then taking at normal tempe it stand for 24 ho	3pcs	
	Box Drop Test	1 Corner 3 Edges (Medium Box)	1 box	

Note: Ta=ambient temperature Tp= Panel temperature

Notes:

1. No dew condensation to be observed.

2. The function test shall be conducted after 4 hours storage at the normal temperature and humidity after removed from the test chamber.

3. No cosmetic or functional defects should be allowed.

4. Total current consumption should be less than twice the initial value.

8.0 Handling Precautions

Safety

If the LCD panel breaks, be careful not to get the liquid crystal fluid in your mouth or in your eyes. If the liquid crystal touches your skin or clothes, wash it off immediately using soap and plenty of water.

Mounting and Design

Place a transparent plate (e.g. acrylic, polycarbonate or glass) on the display surface to protect the display from external pressure. Leave a small gap between the transparent plate and the display surface.

When assembling with a zebra connector, clean the surface of the pads with alcohol and keep the surrounding air very clean.

Design the system so that no input signal is given unless the power supply voltage is applied.

Caution during LCD cleaning

Lightly wipe the display surface with a soft cloth soaked with Isopropyl alcohol, Ethyl alcohol or Trichlorotriflorothane.

Do not wipe the display surface with dry or hard materials that will damage the polariser surface. Do not use aromatic solvents (toluene and xylene), or ketonic solvents (ketone and acetone).

Caution against static charge

As the display uses C-MOS LSI drivers, connect any unused input terminal to VDD or VSS. Do not input any signals before power is turned on. Also, ground your body, work/assembly table and assembly equipment to protect against static electricity.

Packaging

Displays use LCD elements, and must be treated as such. Avoid strong shock and drop from a height. To prevent displays from degradation, do not operate or store them exposed directly to sunshine or high temperature/humidity.

Caution during operation

It is indispensable to drive the display within the specified voltage limit since excessive voltage shortens its life. Direct current causes an electrochemical reaction with remarkable deterioration of the display quality. Give careful consideration to prevent direct current during ON/OFF timing and during operation. Response time is extremely delayed at temperatures lower than the operating temperature range while, at high temperatures, displays become dark. However, this phenomenon is reversible and does not mean a malfunction or a display that has been permanently damaged. If the display area is pushed on hard during operation, some graphics will be abnormally displayed but returns to a normal condition after turning off the display once. Even a small amount of condensation on the contact pads (terminals) can cause an electro-chemical reaction which causes missing rows and columns. Give careful attention to avoid condensation.

Storage

Store the display in a dark place where the temperature is $25^{\circ}C \pm 10^{\circ}C$ and the humidity below 50%RH. Store the display in a clean environment, free from dust, organic solvents and corrosive gases. Do not crash, shake or jolt the display (including accessories).